Version with Markings to Show Changes Made:

In The Claims:

Please cancel claims 29 and 33 and amend Claims 25, 26, and 30 as follows:

25. (Amended) A microbeam assembly adapted to form interconnects between integrated circuit bond pads and substrate contacts, the microbeam assembly comprising:

a carrier; [and]

a plurality of conductive microbeams releasably bonded to the carrier wherein the conductive microbeams are sized and spaced to mate with the bond pads of an integrated circuit, and wherein at least one of said conductive microbeams comprises solder coating a portion thereof;

a solder dam positioned on a surface of said at least one conductive microbeam comprising solder opposite said carrier, said solder dam for preventing solder from wetting along a portion of said microbeam not coated with solder; and

a release layer positioned between said carrier and said conductive microbeams for releasably supporting the conductive microbeams.

26. (Amended) A microbeam assembly according to Claim 25 wherein the carrier is a tape automated bonding (TAB) carrier comprising a release layer formed from a material selected from the group consisting of polymide and parylene [adapted for automated conductive microbeam attachment].

30. (Amended) A microbeam assembly according to Claim 25 [29] wherein the release layer comprises tungsten.

CLT01/4552641v1

Received from < 7043316090 > at 9/6/02 6:45:36 PM [Eastern Daylight Time]